

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1	10/327084	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 14:13
L2	34632478	JP "05067590" A	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 14:13
L3	3	"05067590"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 14:13
S1	78737	molybdenum	USPAT	OR	OFF	2005/12/08 17:34
S2	343987	gate	USPAT	OR	OFF	2005/12/08 11:28
S3	387983	bit or word	USPAT	OR	OFF	2005/12/08 11:29
S4	1889262	line	USPAT	OR	OFF	2005/12/08 11:28
S5	345326	semiconductor	USPAT	OR	OFF	2005/12/08 11:28
S6	37025	S3 near S4	USPAT	OR	OFF	2005/12/08 11:29
S7	5	S6 and (S1 near S2)	USPAT	OR	OFF	2005/12/08 11:30
S8	5	S7 and S5	USPAT	OR	OFF	2005/12/08 11:35
S9	4	S1 near bit	USPAT	OR	OFF	2005/12/08 11:35
S10	2	S1 near word	USPAT	OR	OFF	2005/12/08 11:35
S11	141	aluminum adj neodymium	USPAT	OR	OFF	2005/12/08 11:45
S12	12838	Molybdenum adj tungsten	USPAT	OR	OFF	2005/12/08 11:45
S13	516	S11 or (AL adj nd)	USPAT	OR	OFF	2005/12/08 11:45
S14	19747	S12 or (mo adj w)	USPAT	OR	OFF	2005/12/08 11:46
S15	67	S13 and S14	USPAT	OR	OFF	2005/12/08 11:46
S16	48	S15 and S2	USPAT	OR	OFF	2005/12/08 11:52
S17	0	S16 and (((plasma or dry) near etch) near (molybdenum or gate))	USPAT	OR	OFF	2005/12/08 11:53
S18	15	S16 and (((plasma or dry) near etch))	USPAT	OR	OFF	2005/12/08 11:59
S19	698	S1 and etch and tapered	USPAT	OR	OFF	2005/12/08 11:59
S20	0	S1 near etch near tapered	USPAT	OR	OFF	2005/12/08 11:59
S21	0	S1 near etch near taper	USPAT	OR	OFF	2005/12/08 12:00
S22	17	S1 and etch near taper	USPAT	OR	OFF	2005/12/09 10:43

S23	1	"6,429,057".pn.	USPAT	OR	OFF	2005/12/08 17:40
S24	1	"5,518,860".pn.	USPAT	OR	OFF	2005/12/08 17:40
S25	78737	molybdenum	USPAT	OR	OFF	2005/12/09 10:43
S26	17	S25 and etch near taper	USPAT	OR	OFF	2005/12/09 10:43
S27	1	S26 and ohmic	USPAT	OR	OFF	2005/12/09 10:43
S28	78737	molybdenum	USPAT	OR	OFF	2005/12/09 12:09
S29	17	S28 and etch near taper	USPAT	OR	OFF	2005/12/09 12:15
S30	8919	S28 and array	USPAT	OR	OFF	2005/12/09 12:16
S32	323735	oblique or taper or tapered	USPAT	OR	OFF	2005/12/09 12:16
S33	1410	S30 and S32	USPAT	OR	OFF	2005/12/09 12:17
S34	3	S28 near S32	USPAT	OR	OFF	2005/12/09 12:18
S35	34	S28 near line	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/09 12:19
S36	68	S28 near line	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 12:20
S38	6	S36 and S32	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 12:23
S39	33216	(dry or plasma) near etch	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 12:23
S40	31665	S32 and sidewall	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 12:23
S41	952	S39 and S40	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 12:23

S42	102	S41 and S28	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 12:24
S44	61	S42 and gate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 12:24
S45	28	S44 and (S28 same gate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 12:36
S47	0	pattern near oblique near sidewall	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 12:37
S48	216	oblique near sidewall	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 12:40
S49	2	S48 and S28	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 12:37
S50	1149	taper near sidewall	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 12:40
S51	562	S50 and metal	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 12:40

S52	26	S51 and S28	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 14:11
-----	----	-------------	---	----	----	------------------